

SMD GASKET General Technical Specification [Draft]

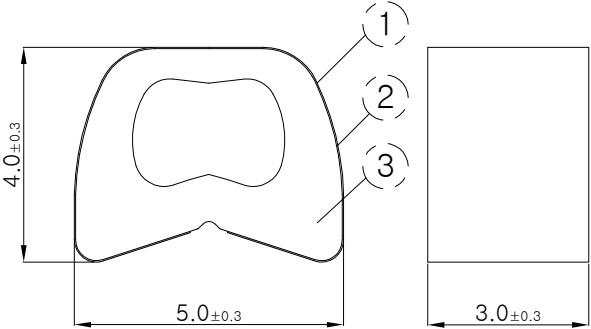
1. General Spec

No.	DESCRIPTION	MATERIAL	REMARKS
1	CONDUCTIVE FILM	POLYIMIDE + Cu + Au	Cu2 μ m, Ni0.3 μ m, Au0.03 μ m
2	SILICONE ADHESIVE	SILICONE	
3	SILICONE RUBBER	SILICONE	

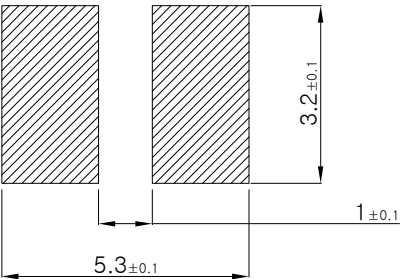
2. Packing Spec

No.	DESCRIPTION	MATERIAL	REMARKS
1	CARRIER TAPE	PS	0.4T X 16mm X 8P
2	COVER TAPE	PS	13.3mm
3	REEL	PS	Ø380 / t2.0

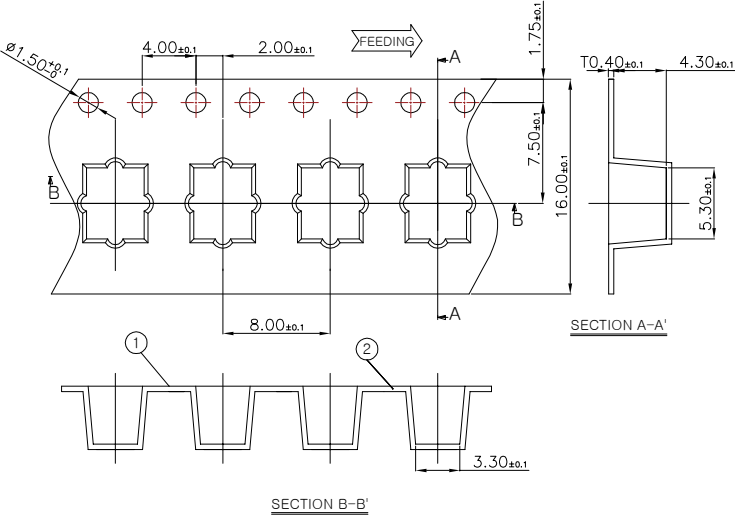
■ Drawing



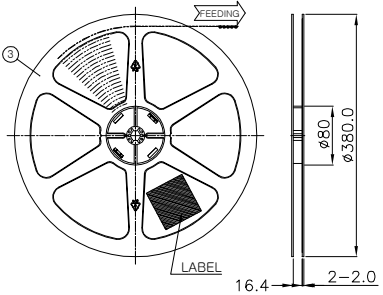
■ RECOMMENDED PCB LAYOUT



■ CARRIER TAPE



■ REEL FOR CARRIER TAPE



- NOTE
- 1. PEELING FORCE : 20 ~ 80g
 - 2. REEL PACKING : 2,500EA / 1REEL

Item		Test Method	Properties
Base Material		N/A	Silicone rubber / PI film
Color		N/A	GOLD
Electrical Resistance test	Original	Precision digital meter HIOKI 3540 mΩ HITESTER	Max. 0.1 Ω
	Thermo-Hygrostat		
	Brine atomizing		
	Thermal Shock		
PCB Bond Strength		UTM	Min. 1,000gf
Restoring Rate		30% Compress for 240 hrs	Min. 90%
UL		UL 94	UL 94-V1 equivalence
RoHS & Halogen		Pb, Cd, Hg, Cr+6, PBBs, PBDEs, Br, Cl	

SCALE	1/1	UNIT	mm
PART No.	MGSMT-5.0-4.0-3.0Au		REV 0
DRAW No.	504030-D		SHEET 1/1